

Title (en)

MANUFACTURING METHOD OF WIRING CIRCUIT BOARD, AND WIRING CIRCUIT BOARD

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER LEITERPLATTE SOWIE ERHALTENDE LEITERPLATTE

Title (fr)

PROCEDE DE FABRICATION DE CARTE A CIRCUIT IMPRIME, ET CARTE AINSI OBTENUE

Publication

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Application

**EP 99970262 A 19991007**

Priority

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Abstract (en)

[origin: WO0021345A1] Fine lines of line width of 40  $\mu\text{m}$  or less are obtained stably without defect on a ceramic substrate, and hence a circuit board of high density and high precision is obtained. The method comprises the steps of: (a) fabricating a ceramic substrate (2), (b) polishing the surface (28) of the ceramic substrate (2) to surface roughness Ra of 0.5  $\mu\text{m}$  or less, (c) forming a photosensitive conductor layer (3a) on the surface of the ceramic substrate (2a), and (d) processing the photosensitive conductor layer (3a) by photolithography, and forming a specified wiring pattern (38). Herein, supposing the roughness curve to be  $Y = f(x)$ , the extracting length of the roughness curve in the center line direction to be L, the central axis of the extracting portion to be X-axis, and the direction vertical to the X-axis to be Y-axis, Ra is the value calculated in the formula (I).

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